

Amendments to the Specification:

Please replace the indicated paragraphs with the amended paragraphs below:

[00171] Figure 18 is a view schematically showing a structure of a cutting apparatus according to Embodiment [[7]] 6.

[00172] Figure 19 is a view for illustrating an operation of the cutting apparatus according to Embodiment [[7]] 6.

[00174] Figure 21 is a front view showing a structure of breaking units 30 and a scribing unit 40 provided in a cutting apparatus according to Embodiment [[8]] 7 of the present invention.

[00363] According to the cutting apparatus according to Embodiment 5, the vertical crack formed right below the scribing line reaches near the upper surface of the glass substrate 90. Therefore, the glass substrate 90 is positively cut after the breaking step which uses a roller according to the present application.

[[<Embodiment 6>]]

[00364] ~~In the cutting apparatus according to Embodiment 2 of the present invention, when a scribing line is formed on the glass substrate 90 by the cutter wheel tip 48a, a pressing force of the pressing roller 32a with respect to the glass substrate 90 is larger than that of the cutter wheel 48a with respect to the glass substrate 90 when the pressing roller 32a of the breaking unit 30 is pressed against the glass substrate 90. In this manner, when the glass substrate 90 is scribed along the line to be scribed by the cutter wheel tip 48a, the vertical crack right below the scribing line extends to reach the upper surface of the glass substrate 90 with the glass substrate 90 bent downward.~~

[00365] ~~In the cutting apparatus according to Embodiment 1 of the present invention, when the scribing line is formed by the irradiation of the laser beam and the spraying of the cooling water, the glass substrate can be bent downward by pressing the pressing roller 32a and the auxiliary roller 33a on the pressing side, provided in the breaking unit 30, against the glass substrate 90.~~

<Embodiment [[7]] 6>

[00384] According to the cutting apparatus of Embodiment 7, a pressing force upon a second surface of the bonded substrate, which opposes a first surface of the bonded substrate, is movable along the scribing line formed on the first surface of the bonded substrate while the first surface of the bonded substrate is held, in this manner, while the pressing force is moved along the scribing line formed on the first surface of the bonded substrate, a pressing force works on the second surface of the bonded substrate which opposes the first surface of the bonded substrate. Therefore, a bending

moment which is generated when the scribing line is formed on the first surface of the bonded substrate and which positively extends a vertical crack extending from the surface of the first surface in the thickness direction of the bonded substrate can work on the brittle substrate to cut the bonded substrate.

<Embodiment [[8]] 7>

After paragraph [00309] and before <Embodiment 2>, insert the following paragraph:

In the cutting apparatus according to Embodiment 1 of the present invention, when the scribing line is formed by the irradiation of the laser beam and the spraying of the cooling water, the glass substrate can be bent downward by pressing the pressing roller 32a and the auxiliary roller 33a on the pressing side, provided in the breaking unit 30, against the glass substrate 90.

After paragraph [00326] and before <Embodiment 3>, insert the following paragraph:

In the cutting apparatus according to Embodiment 2 of the present invention, when a scribing line is formed on the glass substrate 90 by the cutter wheel tip 48a, a pressing force of the pressing roller 32a with respect to the glass substrate 90 is larger than that of the cutter wheel 48a with respect to the glass substrate 90 when the pressing roller 32a of the breaking unit 30 is pressed against the glass substrate 90. In this manner, when the glass substrate 90 is scribed along the line to be scribed by the cutter wheel tip 48a, the vertical crack right below the scribing line extends to reach the upper surface of the glass substrate 90 with the glass substrate 90 bent downward.